IPC-7093

Design and Assembly Process Implementation for Bottom Termination Components

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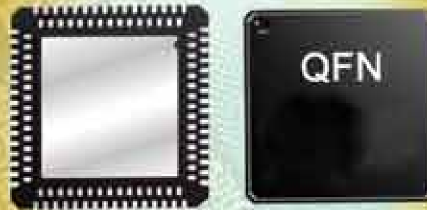

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Design and Assembly Process Implementation for Bottom Termination SMT Components

Developed by the IPC Bottom Termination Components (BTC) Task Group (5-21h) of the Assembly & Joining Processes Committee (5-20) of IPC

Users of this publication are encouraged to participate in the development of future revisions.

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Acknowledgment

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Analog Devices: Figures 4-40, 4-42,6-4, 6-8, 6-11, 6-14, 7-24, 7-27, 7-28, Table 4-9
BEST Inc.: Figures 7-28, 7-33, 7-34, 7-35
Continental Automotive Systems: Figures 7-19, 7-20, 7-21, 7-22
Fairchild Semiconductor: Figure 4-36
Intersil: Figure 4-37
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Martin GmbH: Figure 7-32
Mini Micro Stencil: Figure 7-29
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Table of Contents

1 SCOPE 1

1.1 Purpose 1

1.2 Intent 1

2 APPLICABLE DOCUMENTS 1

2.1 IPC 1

2.2 JEDEC 2

3 SELECTION CRITERIA AND MANAGING BTC IMPLEMENTATION 2

3.1 Terms and Definitions 2

3.1.1 Bottom Termination Components (BTC) 2

3.1.2 Component Mounting Site 2

3.1.3 Conductive Pattern* 2

3.1.4 Land Pattern* 2

3.1.5 Mixed Component-Mounting Technology* 2

3.1.6 Printed Board Assembly 2

3.1.7 Surface Mounting Technology (SMT)* 2

3.2 BTC Executive Summary 2

3.3 Description of Different Component Structures 3

3.4 Total Cost of Ownership 6

3.5 Design and Assembly Process Considerations for QFN Type BTC Packages 6

3.6 Future Needs and Expectations 8

4 COMPONENT CONSIDERATIONS 8

4.1 General Description of Different BTC Packages 8

4.2 Detailed Description and Standards for BTCs 9

4.2.1 Single Row Molded Lead-Frame Based Packaging 9

4.2.2 Multiple Row Molded Lead-Frame Based Packaging 9

4.2.3 JEDEC Publication 95 Design Guide 4.8 10

4.2.4 JEDEC Publication 95 Design Guide 4.23 12

4.2.5 JEDEC Publication 95 Design Guide 4.19 15

4.3 Detailed Description of QFN and SON (DFN) Packages 17

4.3.1 Manufacturing Methods 17

4.3.2 Types of Defects 21

4.3.3 Marking Alternatives 21

4.3.4 Materials Used 21

4.3.5 Solderability Testing 21

4.4 Custom QFN and SON (DFN) 21

4.5 Detailed Description of LGA, QFN and SON (DFN) Substrate-Based Packages 23

4.5.1 Manufacturing Methods for Substrate-Based Packages 23

4.5.2 Types of Defects 24

4.5.3 Marking Alternatives 24

4.5.4 Materials Used 24

4.6 Description of Commercial Variations 24

4.6.1 Detailed Description of MLF®, MLP, and MLFP™ Components 25

4.6.2 Detailed Description of LLC™ and LFCSP™ Components 27

4.7 Packaging and Handling 30

5 MOUNTING STRUCTURES 31

5.1 Types of Mounting Structures 31

5.1.1 Organic Resin Systems 31

5.1.2 Inorganic Structures 31

5.1.3 Layering (Multilayer, Sequential or Build-Up and HDI) 31

5.2 Properties of Mounting Structures 31

5.2.1 Resin Systems 32

5.2.2 Reinforcements 32

5.2.3 Reliability Concerns with High Temperature Lead-Free Soldering 32

5.2.4 Thermal Expansion 33

5.2.5 Moisture Absorption 33

5.2.6 Flatness (Bow and Twist) 34

5.3 Surface Finishes 34

5.3.1 Hot Air Solder Leveling (HASL) 35

5.3.2 Organic Surface Protection (Organic Solderability Preservative) Coatings 36

5.3.3 Noble Metal Platings/Coatings 36

5.4 Solder Mask 38

5.4.1 Wet and Dry Film Solder Masks 38

5.4.2 Photoimageable Solder Masks 40

5.4.3 Registration 41

5.4.4 Via Protection 41

5.5 Thermal Spreader Structure Incorporation (e.g., Metal Core Boards) 44

5.5.1 Lamination Sequences 44

5.5.2 Heat Transfer Pathway 44

5.5.3 Thermal Pad Attachment 44

5.5.4 Thermal Vias 45

5.6 Solderless Interconnections Systems 45

6 PRINTED CIRCUIT ASSEMBLY DESIGN CONSIDERATIONS 46

6.1 BTC Part Description 46

6.1.1 BTC Package Variations 46

6.1.2 Termination Formats 48

6.1.3 Mounting Conditions 48

6.1.4 Package Tolerances 54

6.1.5 Attachment Techniques 57

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